

#31705 87346
D/CMS

501.39868X00

J1000 U.S. PTO
09/850162
05/08/01


IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: SAITO et al.

Serial No.: Not yet assigned

Filed: On even date

For: A SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND A
METHOD OF MANUFACTURING THE SAME

INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR 1.97 & 1.98

Assistant Commissioner for Patents
Washington, D.C. 20231

May 8, 2001

Sir:

In the matter of the above-identified application, applicants are submitting herewith copies of the documents listed in the attached form equivalent to Form PTO-1449 for the Examiner's consideration.

This information disclosure statement is being submitted with the new application.

To the extent the documents listed on the attached form equivalent to Form PTO-1449 are not in the English language, the requirement of 37 CFR 1.98(a)(3) for a concise explanation of the relevance is satisfied by an English language abstract or translation of the documents and the discussion of these documents in the specification, for example, on pages 1 and 2.

It is respectfully requested that this information disclosure statement be considered by the Examiner.

Please charge any shortage in the fees due in connection with the filing of this paper, including extension of time fees, to the deposit account of Antonelli, Terry, Stout &

Kraus Deposit Account No. 01-2135 (Case: 501.39868X00), and
please credit any excess fees to such deposit account.

Respectfully submitted,

ANTONELLI, TERRY, STOUT & KRAUS LLP



Gregory E. Montone
Registration No. 28,141

GEM/vlc
(703) 312-6600

Attachments

FORM PTO-1449 U.S. Department of Commerce
(Rev. 4/92) Patent and Trademark Office

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(Use several sheets if necessary)

ATTY. DOCKET NO.
501.39868X00

SERIAL NO.
n.y.a.

**APPLICANT
SAITO et al.**

FILING DATE
May 8, 2001

GROUP

1000 U.S. Pro
09/850162
05/08/01

U.S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

Saito et al., "Impact of Low Pressure Long Throw Sputtering Method on Submicron Copper Metallization", Proceedings of IITC, June 1998, pp. 98-160-98-162.

Yoshihiko et al., "Process of Completely Covered Cu Wiring" (English translation)

EXAMINER

DATE CONSIDERED

EXAMINER: Initial if citation is considered, draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.